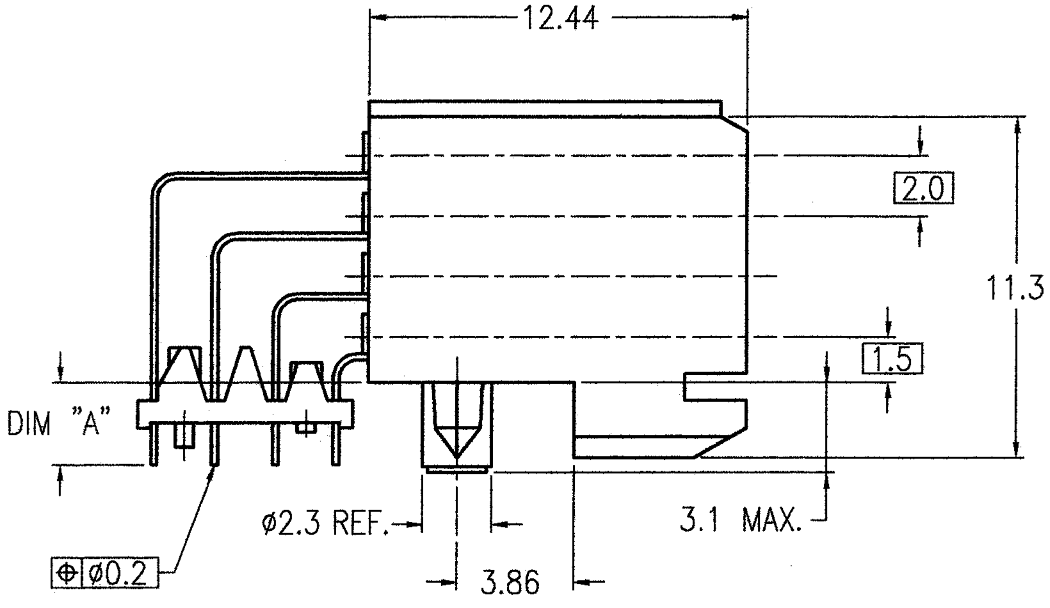
PRODUCT NO.	PLATING CONTACT AREA	UNDER PLATING
93336-1YZ	0.8μm GOLD	1.3μm Ni MIN.
93336-2YZ	2.0μm GOLD	1.3μm Ni MIN.
93336-3YZ	1.3μm GOLD	1.3μm Ni MIN.
93336-9YZ	0.8μm GXT	1.3μm Ni MIN.

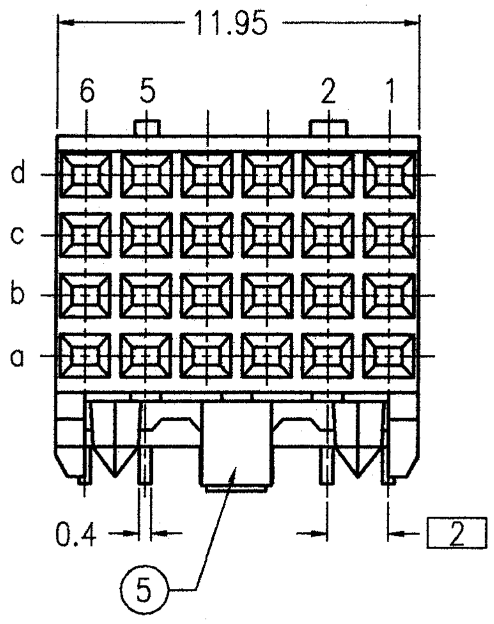
PC BOARD VERSIONS

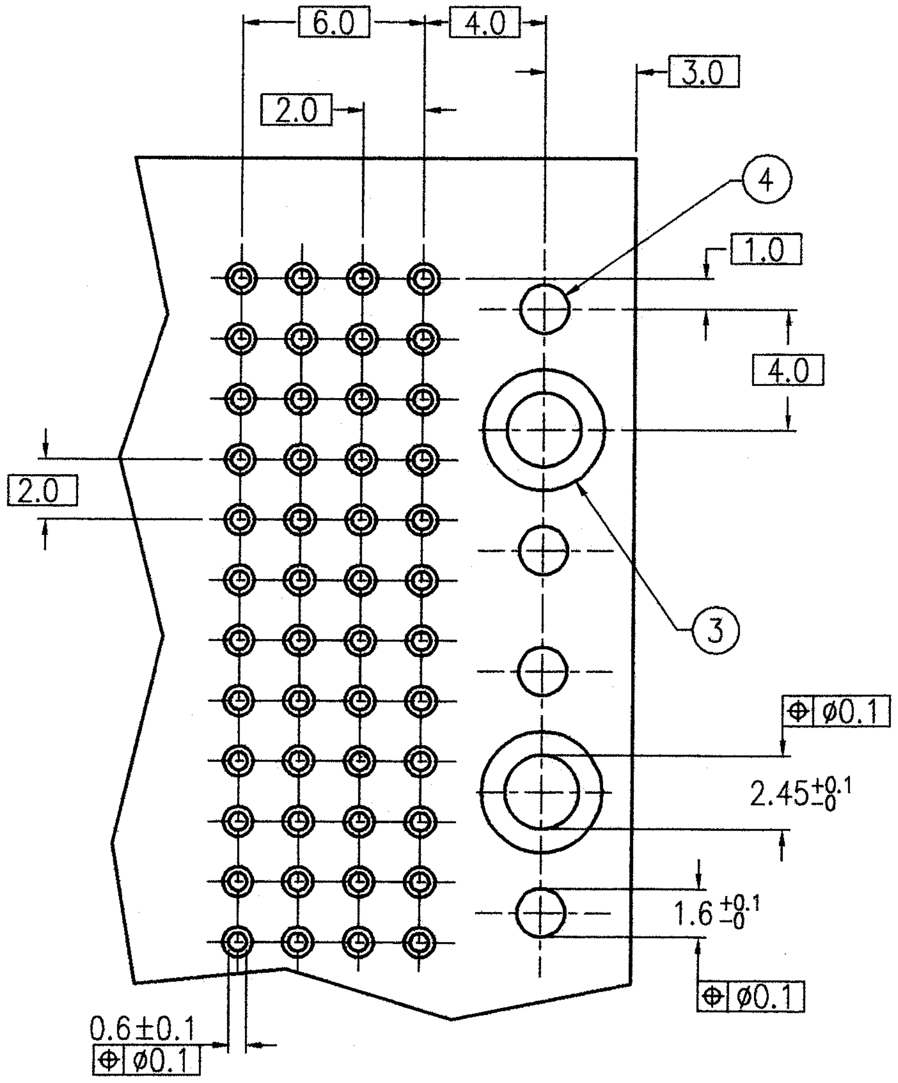
PRODUCT NO.	PCB THICKNESS	DIM "A"
93336-X01	1.6	2.73
93336-X11	2.4	3.53

REVISIONS

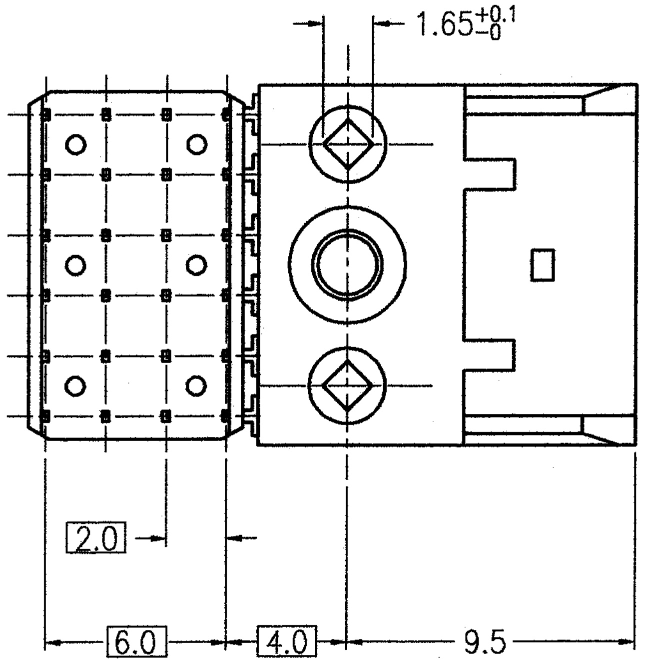
REV	DESCRIPTION	ECN	BY	DATE
A	RELEASED	J40231	S.S	7/21/'94
B	REVISED	J80208	A.Y	5/ 8/'98







RECOMMENDED P.C. BOARD LAY-OUT



NOTE

1 MATERIAL
HOUSING : LCP UL94V-0
CONTACT : PHOSPHOR BRONZE

2 PLATING
SOLDER TAIL : Sn-Pb 2 ~8μm

③ PLATED THROUGH HOLES
LAND SIZE : ⌀4±0.1mm
(SQUARE LAND SIZE : □3mm)
PLATING : Sn-Pb 10 ~15μm

④ UNPLATED THROUGH HOLES

⑤ DIP RING (1pc.)
MATERIAL : PHOSPHOR BRONZE t=0.15mm
PLATING : Sn-Pb 2 ~3μm

SHEET INDEX	ISSUE	B
	SH NO.	1

TOLERANCES UNLESS OTHERWISE SPECIFIED
LINEAR ±0.2
ANGLES ±2°

MAT SEE NOTE 1. &⑤
FINISH SEE NOTE 2. &⑤

		DATE
DR	S. Shu	7/21/'94
ENGR	A. Yodogawa	5/ 8/'98
CHK	Yamamoto	8/11/'98
APPD	Id. Amano	8/11/'98

CUSTOMER COPY
THIRD ANGLE PROJ
UNIT MM ~~INCH~~

BERG
ELECTRONICS

TITLE METRAL R/A FEMALE SIGNAL
4X6 POS. DIP RING TYPE

SCALE	SIZE	DWG. NO.	REV	SHEET
4/1	B	93336	B	1 OF 1

DO NOT SCALE PRINT

DF-004A REV C